

AMENDMENTS TO THE CLAIMS

In the claims:

This Listing of Claims replaces all prior versions, and listings, of the claims in this application.

Listing of Claims:

1-7. (Canceled)

8. (Currently Amended) An apparatus, comprising:

a heat spreader comprising heat conductive material and a contiguous wall structure extending from a surface of the heat spreader;

a package substrate;

a flexible material in contact with the surface of the heat spreader and the package substrate, the flexible material defining a perimeter of a cavity; ~~and~~

a circuit substrate disposed within the cavity; and

at least two stand-offs interdisposed between the surface of the heat spreader and the circuit substrate.

9. (Previously Presented) The apparatus of claim 8, wherein the flexible material comprises polymeric sealant material.

10. (Previously Presented) The apparatus of claim 8, wherein the heat spreader is plated with nickel.

11. (Previously Presented) The apparatus of claim 8, wherein the heat spreader is coated with a heat-conductive organic material.

12-17. (Canceled)

18. (Currently Amended) A semiconductor package, comprising:
a substrate having a surface;

at least one semiconductor device coupled to the surface of the substrate;

a cover coupled to the surface of the substrate through a flexible sealant material, the flexible material contacting a surface of the cover and the surface of the substrate and creating a space between the substrate and the cover, the semiconductor device residing within the space, and the cover comprised of a heat-conductive material; and

at least two stand-offs interdisposed between the surface of the cover and the semiconductor device; and

a thermal interface material comprising metal particles disposed between a surface of the semiconductor device and the surface of the cover,

wherein the cover comprises a contiguous attachment structure extending from the surface into the flexible material.

19. (Original) The semiconductor package of claim 18, wherein the cover is a heat spreader.

20-23. (Canceled)

24. (Previously Presented) The apparatus of claim 8 further comprising:

a thermal interface material comprising metal particles disposed between a surface of the circuit substrate and the surface of the heat spreader.